

FIT Hon Teng Limited
鴻騰六零八八精密科技股份有限公司

1Q23 Results Announcement

二零二三年第一季度業績發佈會



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Agenda

1Q23 Financial Overview

Strategy Update

2Q23 Guidance

News Update

ESG

Q&A Section

Financial Highlight

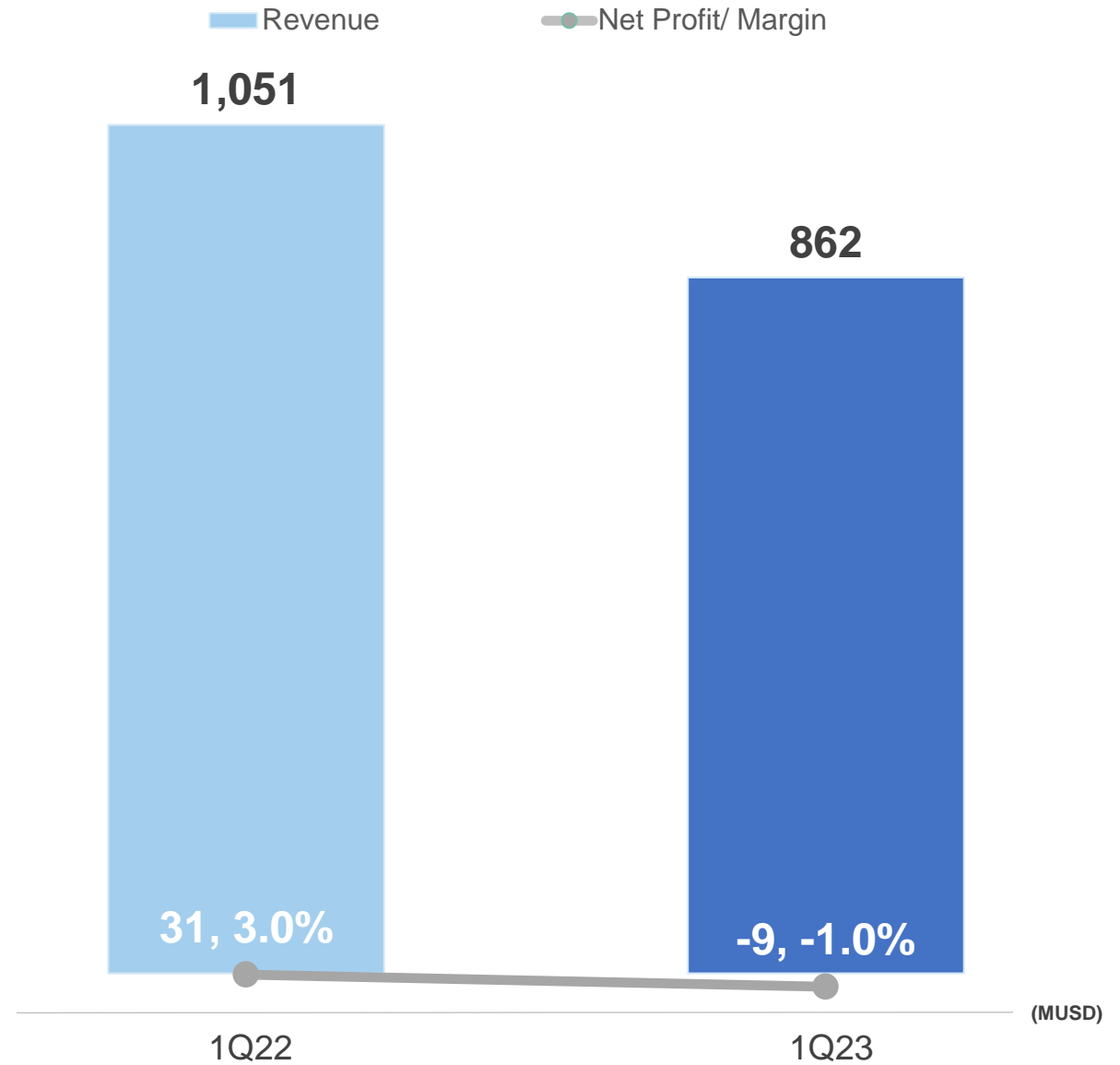
1Q23 Financial Highlight

REVENUE

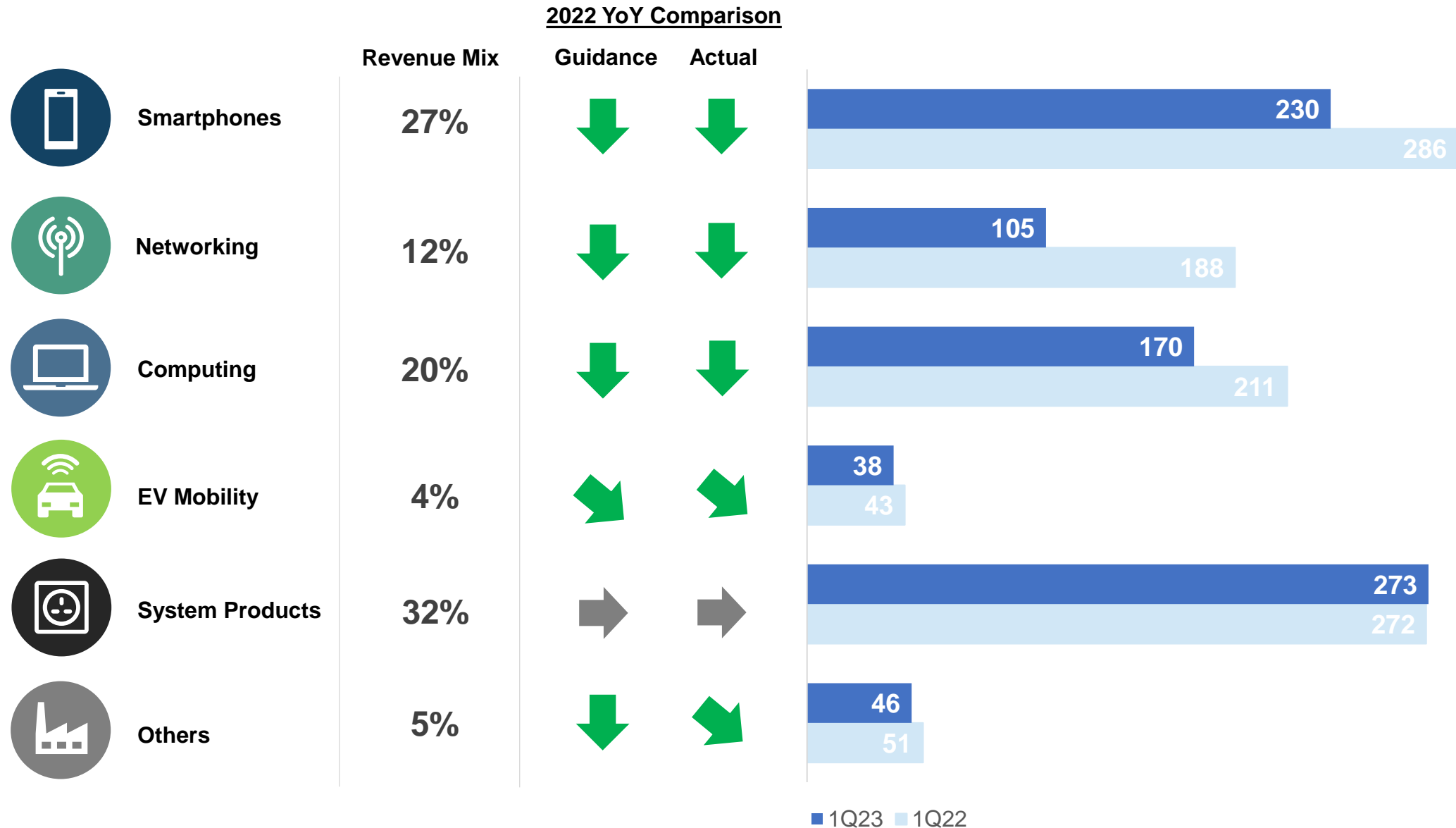
-18%

NET INCOME

-129%

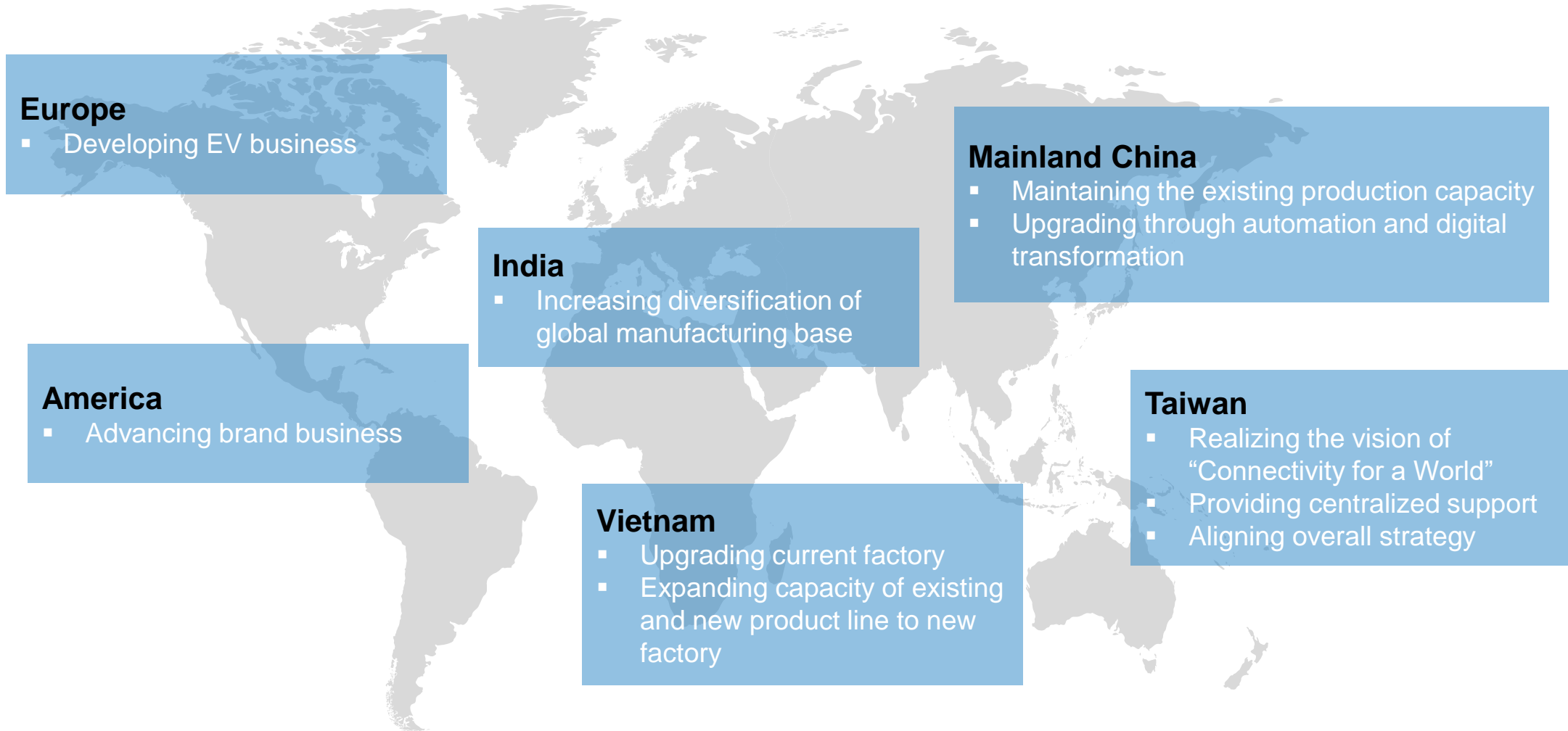


1Q23 Segment Performance



Strategy Updates

Expand Global Services as Industry Trend Diversifies Footprint



1Q23 3+3 Strategy Execution



EV Mobility

- M&A closing execution
- Enhancing competitiveness through M&A
- Product line expansion



New Generation 5G AIoT

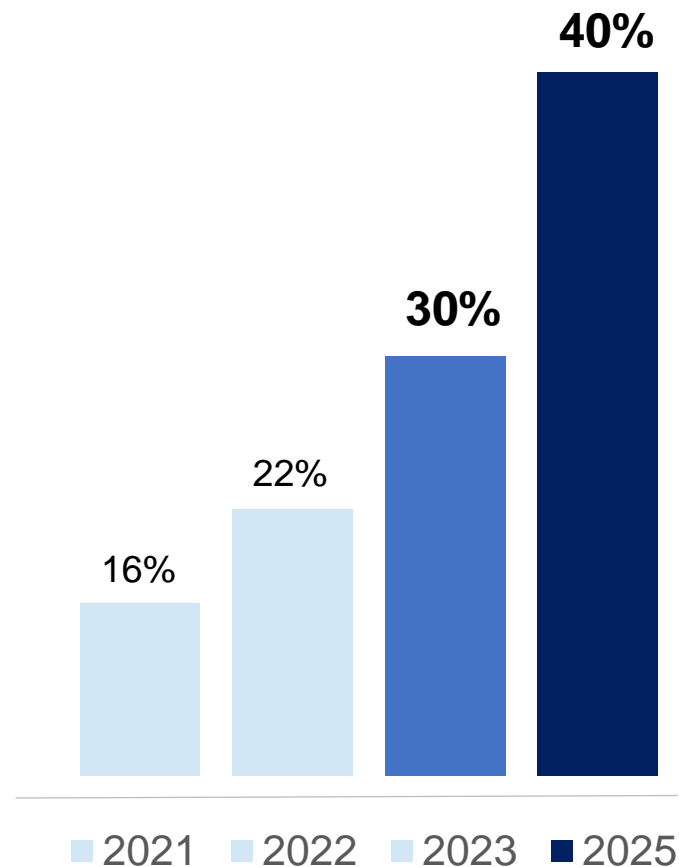
- Key focus for mid-term profit growth
- DDR & CPU new platform development
- New business opportunities with certified products



Audio

- Preparation of global service expansion

Revenue Mix Forecast Update



5G AioT Certified Products Meet Industry Trend



Energy Saving



CPU socket & DDR passed the liquid cooling environment test



Power Efficiency



MCRPS connectors mass-produced & entered association standards



Open Standard



Opened an alliance corresponding M-XIO EDSFF product matching

2Q23 Guidance

2023 Full Year Financials Guidance Recap



Full Year Guidance Updates by Segment



Smartphones



Networking



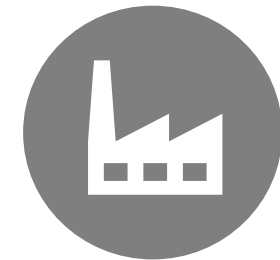
Computing



Mobility



System Products

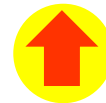
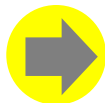


Others

2023 YoY



Guidance in
March 2023



2Q23 Guidance

↑ > +15% ↑ +5 – 15% → 0 ± 5 ↓ -5 – 15% ↓ > -15%



Smartphones



Networking



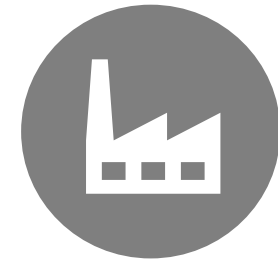
Computing



Mobility



System Products



Others

2Q23 YoY



1H23 YoY



News Updates

Recent Announcements

鴻海旗下鴻騰精密 砸4億美元擴張越南、印度產能



鴻海 (2317) 集團旗下鴻騰精密科技 (6088-HK) 宣佈擴大其全球服務計畫，公告以4億美元（新台幣約122.08億元）注資其全資新加坡全資子公司Foxconn Interconnect Technology Singapore Pte. Ltd.，擴張印度、越南製造基地，以回應近期電子製造業多元化全球製造基地的趨勢。市場盛傳，在印度部分，鴻騰精密本次擴張產能主要是因應拿下蘋果AirPods訂單。

6 April - Global Expansion

鴻騰斥資7.22億印度買地 強化新事業發展

2023/04/21 20:49



鴻騰精密宣布斥資7.22億元，在印度購地。（圖取自鴻騰官網）

【記者方肇傑／台北報導】鴻海（2317）旗下鴻騰精密今天宣布斥資7.22億元，在印度泰倫哥納邦（Telangana）購置186.7英畝（約75萬5537平方公尺）土地，用來興建工廠、研發中心及宿舍，作為強化電動車、聲學、5G智慧物聯網領域業務的其中1個環節。

21 April - Land Purchase in India

鴻海旗下鴻騰出脫Autotalksf全數持股 處分利益1.5億元

鉅亨網記者彭昱文 台北 2023/05/03 23:14



鴻海旗下鴻騰出脫Autotalks持股 處分利益約1.5億元。（鉅亨網資料照）



Tag 鴻海 鴻騰 autotalks

鴻海 (2317-TW) 旗下鴻騰精密 (FIT) (06088-HK) 今 (3) 日公告，處分以色列車聯網晶片設計商 Autotalks 全數持股，處分利益 500 萬美元、約新台幣 1.5 億元。

鴻騰是在 2021 年 9 月與 Autotalks 簽署協議，投資 Autotalks 1000 萬美元，強化布局車用及微移動車聯網 (micro-mobility)。不過，合作不到兩年，鴻騰即出脫全數持股，公司表示，目的為實現投資。

3 May – Autotalks

Q&A section



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Foxconn Interconnect Technology Limited (Incorporated in the Cayman Islands and carrying on business in Hong Kong as FIT Hon Teng Limited)

鴻騰精密科技股份有限公司 (於開曼群島成立，並以鴻騰六零八八精密科技股份有限公司於香港經營業務)

Appendix

Statement of Comprehensive Income

(M'USD)	1Q23	1Q22	YoY
Revenue	862	1,051	-18%
Gross Profit	136	166	-18%
Gross Profit Margin	15.8%	15.8%	0%
Operating Profit	6	34	-82%
Profit before Tax	(3)	39	-108%
Income Tax Expense	(6)	(8)	-25%
Profit for the Year	(9)	31	-129%
Profit Attributed to :			
Owners of the Company	(9)	31	-129%
Non-controlling Interests	0	0	N/A
Basic EPS	(0.13)	0.43	-130%

Balance Sheet

(K'USD)	As of 31 Mar 2023	As of 31 Mar 2022	YoY
Cash and Cash equivalents	981,695	1,171,751	-16%
Inventory	863,098	1,006,521	-14%
Receivables	604,110	748,576	-19%
Other current assets	128,420	261,501	-51%
Non-current assets	1,755,644	1,945,420	-10%
Total Assets	4,332,967	5,133,769	-16%
Current Liabilities	(1,911,162)	(2,046,878)	-7%
Non-Current Liabilities	(63,772)	(668,877)	-90%
Total Liabilities	(1,974,934)	(2,715,755)	-27%
Equity	2,358,033	2,418,014	-2%

Cash Conversion Cycle

Days	1Q23	1Q22
Average inventory turnover days	115	103
Average trade receivables turnover days	70	77
Average trade payables turnover days	71	75

Terminology

SiC	Silicon Carbide
48V-DC	48 Voltage DC Power Supply
M-CRPS	Common Redundant Power Supply
DC-HMS	Modular Hardware System
PCIe	Peripheral Component Interconnect Express
U.2	Extension of the SATA and SAS storage interfaces
M-XIO	Extensible IO (near side “IO”)
EDSFF	Enterprise & Data Centre SSD Form Factor